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1. Name of conveying party(ies)	2. Name and address of receiving party(ies)					
Matsuda, Kouichi	Name: Sony Corporation					
	Internal Address:					
Additional name(s) of conveying party(ies) attached? Yes / No 3. Nature of conveyance/Execution Date(s):	Street Address: 7-35 Kitashinagawa 6-Chome, Shinagawa					
Execution Date(s) 8/12/06	Office L Address. To Mashinggawa o Onome, Onnegawa					
✓ Assignment Merger						
Security Agreement Change of Name	City: Tokyo State:					
Joint Research Agreement						
Government Interest Assignment	otate.					
Executive Order 9424, Confirmatory License	Country: JapanZip:					
Other	Additional name(s) & address(es) attached? Yes Vo					
	document is being filed together with a new application.					
A. Patent Application No.(s)	B. Patent No.(s)					
11/531,609						
Additional numbers at	 ached?					
5. Name and address to whom correspondence	6. Total number of applications and patents					
concerning document should be mailed:	involved: 1					
Name: Bell, Boyd & Lloyd LLC	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00					
Internal Address:	Authorized to be charged by credit card					
	✓ Authorized to be charged to deposit account					
Street Address; P.O. Box 1135	Enclosed					
	None required (government interest not affecting title)					
City: Chicago	8. Payment Information					
	a. Credit Card Last 4 Numbers					
	Expiration Date					
Phone Number:	b. Deposit Account Number <u>02-1818</u>					
Fax Number: <u>312.827.8185</u>	Authorized User Name					
Email Address:						
9. Signature:	October 5, 2006 Date					
Signature	Total number of pence including course					
Thomas C. Basso - No.: 46,541  Name of Person Signing	sheet, attachments, and documents:					

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P.02

S06P1149US00

Docket Number: 112857-924

## ASSIGNMENT

•	WHE	REAS, I, as a belo	w named inventor,	residing at the addres	s stated next to	my name, am a sole i	inventor (if
only	one name is listed INFORF EXON	below) or a joint in PROCESSING ME	nventor (if plural n IHOD, INFORMA	ames are listed below TION-PROCESSING	of certain new APPARATUS,	and useful improvem	ients in UM,
	אאסבי זכום רוואא			<del></del>	<u> </u>	· <del></del>	_ <del></del>

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 11/531,609 Filing Date: September 13, 2006

This assignment executed on the dates indicated below.

Kouichi MATSUDA	and the second s
Name of first or sole inventor	 Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of first or sole inventor  Signature of first or sole inventor	Date of this assignment

PATENT REEL: 018365 FRAME: 0482

**RECORDED: 10/05/2006**